



NEWS RELEASE

# Xperi Announces DBI® Ultra Die-to-Wafer Hybrid Bonding Technology for High Performance Computing

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Low Profile High Bandwidth Memory (HBM) stacks of 12 and 16 die are now possible

SAN JOSE, Calif.--(BUSINESS WIRE)-- Xperi Corporation (Nasdaq: XPER) is proud to announce Invensas DBI Ultra, a revolutionary, patented die-to-wafer hybrid bonding, 3D interconnect technology platform ushering in a new era of homogeneous and heterogeneous 3D integration unachievable before today. Among a wide range of applications, DBI Ultra makes it possible to manufacture 12- and 16-high HBM stacks while meeting the demanding packaging height and performance requirements for next generation, high-performance computing.

DBI Ultra is an enabling low-temperature, low profile die-to-wafer and die-to-die hybrid bonding technology platform. By eliminating the need for copper pillars and underfill, DBI Ultra can enable a dramatically thinner stack than conventional approaches. DBI Ultra also allows the stacking of known good die that are the same or different sizes, processed on fine or coarse wafer process technology nodes, or manufactured on the same or different wafer sizes while readily scaling down to 1 um interconnect pitch.

DBI Ultra will be showcased at the Xperi booth at ECTC 2019 Exhibits in the Cosmopolitan Hotel, Las Vegas, NV on May 29 and 30.

"We are thrilled to introduce DBI Ultra, the ultimate 3D interconnect and integration solution," said Craig Mitchell, President of Invensas, a wholly owned subsidiary of Xperi Corporation. "This production-worthy die-to-wafer hybrid bonding platform allows the semiconductor industry to extend beyond Moore's Law, providing unprecedented 2.5D and 3D integration flexibility required for next generation electronics."

DBI wafer-to-wafer hybrid bonding, the predecessor to DBI Ultra, is already successfully incorporated into image sensors shipping in hundreds of millions of smartphones around the world. DBI Ultra is poised to realize similar

success in 3D stacked memory, such as 3DS DRAM and High Bandwidth Memory, as well as in 2.5D and 3D applications requiring the integration of memory with CPUs, GPUs, FPGAs, or SoCs.

For more information about Xperi and its technologies platforms, please visit [www.xperi.com](http://www.xperi.com).

## About Xperi Corporation

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